

Title (en)  
INSULATING ADHESIVE COMPOSITION FOR METAL-BASED COPPER CLAD LAMINATE (MCCL), COATED METAL PLATE USING SAME, AND METHOD FOR MANUFACTURING SAME

Title (de)  
ISOLIERENDE KLEBSTOFFZUSAMMENSETZUNG FÜR KUPFERKASCHIERTES LAMINAT AUF METALLBASIS, BESCHICHTETE METALLPLATTE DAMIT UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)  
COMPOSITION ADHÉSIVE ISOLANTE POUR UN STRATIFIÉ PLAQUÉ CUIVRE À BASE MÉTALLIQUE (MCCL), PLAQUE MÉTALLIQUE REVÊTUE L'UTILISANT ET SON PROCÉDÉ DE FABRICATION

Publication  
**EP 2799509 A4 20150902 (EN)**

Application  
**EP 12861419 A 20121221**

Priority  
• KR 20110144908 A 20111228  
• KR 2012011310 W 20121221

Abstract (en)  
[origin: EP2799509A1] The present invention relates to an insulating adhesive composition for metal printed circuit board, an adhesive-coated metal plate using the same, and a method for manufacturing the adhesive-coated metal plate. The adhesive composition according to the present invention forms an adhesive layer that is excellent in terms of adhesion to a copper foil, electrical insulating properties, and thermal resistance. The composition contains a specific epoxy resin, a curing agent and alumina. According to the present invention, in coating the metal plate with the solvent type adhesive, a roll coating method is used to perform a continuous coating process on the metal plate, thereby improving productivity when compared to the general method using a sheet type adhesive film.

IPC 8 full level  
**C09J 163/00** (2006.01); **C08G 59/14** (2006.01); **C09J 7/00** (2006.01); **C09J 11/04** (2006.01); **C23C 26/00** (2006.01)

CPC (source: EP KR US)  
**C08G 59/1433** (2013.01 - EP US); **C08G 59/145** (2013.01 - EP US); **C09J 7/28** (2017.12 - KR); **C09J 11/04** (2013.01 - KR US); **C09J 11/06** (2013.01 - KR); **C09J 11/08** (2013.01 - KR); **C09J 163/00** (2013.01 - KR); **C09J 163/10** (2013.01 - US); **C23C 26/00** (2013.01 - EP US); **C23C 28/30** (2013.01 - EP US); **H05K 1/056** (2013.01 - US); **H05K 3/386** (2013.01 - EP US); **H05K 3/44** (2013.01 - US); **C08K 2003/2227** (2013.01 - KR); **C08K 2201/005** (2013.01 - KR); **Y10T 428/263** (2015.01 - EP US); **Y10T 428/2804** (2015.01 - EP US)

Citation (search report)  
• [X] WO 2010001992 A1 20100107 - ASAHI KASEI CHEMICALS CORP [JP], et al  
• [X] EP 0122483 A1 19841024 - TORAY SILICONE CO [JP]  
• See references of WO 2013100502A1

Cited by  
WO2020115041A1; GB2579582B; US10403850B2; US11223028B2; WO2020216691A1; DE102017221072A1; WO2019101913A1; EP3741803A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**EP 2799509 A1 20141105; EP 2799509 A4 20150902**; CN 104144998 A 20141112; JP 2015507677 A 20150312; KR 101332507 B1 20131126; KR 20130076350 A 20130708; US 2014377453 A1 20141225; WO 2013100502 A1 20130704

DOCDB simple family (application)  
**EP 12861419 A 20121221**; CN 201280070887 A 20121221; JP 2014549978 A 20121221; KR 20110144908 A 20111228; KR 2012011310 W 20121221; US 201214369411 A 20121221